# TEXAS INSTRUMENTS



## TPS60240, TPS60241 TPS60242, TPS60243

SLVS372B - JUNE 2001 - REVISED JANUARY 2002

# 170-μVrms ZERO-RIPPLE SWITCHED CAP BUCK-BOOST CONVERTER FOR VCO SUPPLY

## FEATURES

- Wide Input Voltage Range:
  - 1.8 V To 5.5 V for 2.7-V, 3-V, 3.3-V Output (TPS60240/2/3)
    - 2.7 V To 5.5 V for 5-V Output (TPS60241)
- 170-µVrms Zero Ripple Output: – at 20 Hz to 10 MHz Bandwidth
- Minimum Number of External Components

   No Inductors
  - Only Small Ceramic Chip Capacitors
- Up to 90% Efficiency
- Regulated 3.3-V (TPS60240), 5-V (TPS60241), 3-V (TPS60243), and 2.7-V (TPS60242) Output Voltage With ±2.5% Accuracy Over Load
- Up to 25-mA Output Current
- Shutdown Mode: 0.1 μA Typical
- Thermal Protection and Current Limit
- Microsmall 8-Pin MSOP Package
- EVM Available TPS60241EVM-194

## **APPLICATIONS**

- VCO and PLL Power for:
  - PDA Phones
  - Cellular Phones
  - PCMCIA Modems
- Smartcard Readers

#### typical application circuit

- Digital Cameras
- MP3 Players
- SIM Modules
- Electronic Games
- Memory Backup
- Handheld Meters
- Bias Supplies

## DESCRIPTION

The TPS6024x is a switched capacitor voltage converter, ideally suited for VCO and PLL applications that require low noise and tight tolerances. Its dual-cap design uses four ceramic capacitors to provide ultralow output ripple yet high efficiency, while eliminating the need for inefficient linear regulators.

A wide input supply voltage range of 2.7 V to 5.5 V makes the TPS6024x ideal for lithium-based battery applications. The TPS60240/2/3 operates down to 1.8 V, supporting a 3.3-V, 2.7-V, 3-V output from two-cell, nickel- or alkaline-based chemistries. The devices work equally well for low EMI dc/dc step-up conversion without the need for an inductor. The high switching frequency (typical 160 kHz) promotes the use of small surface-mount capacitors, saving board space. The converter's shutdown mode conserves battery energy.





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#### description(continued)

The devices are thermally protected and current-limited for reliable operation even under persisting fault conditions. Normal quiescent current (ground pin current) is only 250  $\mu$ A, and typically 0.1  $\mu$ A in shutdown mode. The TPS6024x devices come in a thin, 8-pin MSOP (DGK) package with a component height of only 1,1 mm.

#### DGK PACKAGE (TOP VIEW)

V <sub>OUT</sub>	1 0	8	□□ C <sub>2+</sub>
EN 🗆	2	7	□ C <sub>1+</sub>
C <sub>2−</sub> □□□	3	6	
GND 🖂	4	5	C <sub>1-</sub>

#### **AVAILABLE OPTIONS**

TA	PART NUMBER <sup>†</sup>	PACKAGE MARKING	PACKAGE	
-40°C to 85°C	TPS60241DGKR	AUB	DGK (8-pin MSOP)	5 V
	TPS60240DGKR	ATM	DGK (8-pin MSOP)	3.3 V
-40°C to 85°C	TPS60242DGKR	AYF	DGK (8-pin MSOP)	2.7 V
	TPS60243DGKR	AYG	DGK (8-pin MSOP)	3 V

<sup>†</sup> This package type is available taped and reeled only. Quantity is 2500 units per reel (e.g., TPS60241DGKR). The devices are also available on mini reel with 250 units per reel. To order this packaging option, replace the R with a T in the part number (e.g., TPS60261DGKT).



#### functional block diagram



### **Terminal Functions**

TERMI	NAL			
NAME	NO.	1/0	DESCRIPTION	
C <sub>1+</sub>	7		Positive terminal of the flying capacitor C1	
C <sub>1-</sub>	5		Negative terminal of the flying capacitor C1	
C <sub>2+</sub>	8		Positive terminal of the flying capacitor C2	
C <sub>2-</sub>	3		Negative terminal of the flying capacitor C2	
EN	2	-	Enable terminal, active high	
GND	4		Ground	
VIN	6	I	Supply voltage input TPS60241: 2.7 V to 5.5 V, TPS60240/2/3: 1.8 V to 5.5 V. Bypass V <sub>IN</sub> to GND with a 1- $\mu$ F external capacitor (C <sub>I</sub> ).	
VOUT	1	0	Regulated power output. Bypass VOUT to GND with a 1- $\mu$ F external filter capacitor (C <sub>O</sub> ). TPS60241: regulated 5-V output, TPS60240: regulated 3.3-V output, TPS60242: regulated 2.7-V output, TPS60243: regulated 3-V output	



#### detailed description

#### operating principle

The TPS6024x charge pump is a fixed-frequency, dual-phase charge pump that provides 25 mA of continuous supply current for low-noise applications such as VCOs used in cell phones and wireless appliances.

Low-noise operation results from using a proprietary dual-phase charge pump topology that relies on an operational amplifier in the feedback loop to reduce ripple. During the first phase,  $C_1$  is charged to the supply voltage. Terminal  $C_{1+}$  is connected to  $V_{IN}$ , and  $C_{1-}$  is connected to GND. In the second phase,  $C_{1-}$  is connected to the output of the operational amplifier, and  $C_{1+}$  is connected to  $V_{OUT}$ . The operational amplifier then adjusts its output until the output  $V_{OUT}$  delivers the correct voltage to make the resistor divided feedback point equal to the reference voltage. During this second phase,  $C_2$  is charged to supply voltage. Terminal  $C_{2-}$  is connected to  $V_{IN}$ . Phase one is then repeated with  $C_2$ , now acting to provide charge to the output in place of  $C_1$ , which is connected to the supply. The dual-phase operation lowers the output ripple voltage significantly compared to a standard single-phase charge pump. In addition, the linear feedback of the operational amplifier eliminates the ripple during discharge of the output capacitor ( $C_0$ ).

#### shutdown

Driving EN low disables the converter. This disables the internal circuits and reduces input current to typically 0.1  $\mu$ A. In this mode, the load is disconnected from the supply voltage. The device exits shutdown once EN is set to a high level.

#### start-up procedure

The converter is enabled when EN is set from logic low to high. The start-up time to reach 90% of the nominal output voltage is typically 0.5 ms at load currents lower than 10 mA and with an output capacitor of 1  $\mu$ F. Increasing the values of C<sub>O</sub> delays the start-up time.

#### absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>DD</sub>	
Power dissipation, P <sub>D</sub>	Internally limited
Voltage EN	–0.3 V to 6 V
Voltage C <sub>2-</sub> , C <sub>1-</sub>	
Voltage C <sub>2+</sub> , C <sub>1+</sub>	$\dots$ -0.3 V to V <sub>I</sub> , V <sub>O</sub> or 5.5 V, whichever is lowest
Junction temperature, T <sub>J</sub>	125°C
Storage temperature, T <sub>stg</sub>	–65°C to 150°C
Shortcircuit output current	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
DGK	376 mW	3.76 mW/°C	207 mW	150 mW

NOTE: The thermal resistance junction to ambient of the DGK package is R<sub>TH-JA</sub> = 150°C/W.



#### recommended operating conditions

			MIN	NOM	MAX	UNIT
VI Input voltage rar		TPS60240, TPS60242, TPS60243	1.8		5.5	V
	Input voltage range	9 TPS60241			5.5	V
lo	Output current range	All devices		25		mA
Cl	Input capacitor			1		μF
C <sub>1</sub> , C <sub>2</sub>	Flying capacitors			1		μF
CO	Output capacitor			1		μF
TA	Operating temperature range		-40		85	°C

# electrical characteristics for TPS6024X at T<sub>A</sub> = 25°C, C<sub>I</sub> = C<sub>O</sub> =1 $\mu$ F, C<sub>1</sub> = C<sub>2</sub> = 1 $\mu$ F (unless otherwise noted), limits apply over the specified temperature range, –40°C to 85°C

	PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT	
		TPS60240 Assu	ured start-up	$I_{O} \le 5$ mA, R <sub>L</sub> = 600 $\Omega$	1.8		5.5		
.,		TPS60241 Assu	ured start-up	$I_{O} \le 12 \text{ mA}, \text{ R}_{L} = 417 \Omega$	2.7 1.8		5.5	v	
VI	Input voltage	TPS60242 Assu	ured start-up	$I_{O} \le 12 \text{ mA}, \text{ R}_{L} = 225 \Omega$			5.5		
		TPS60243 Assu	ured start-up	$I_{O} \le 10 \text{ mA}, \text{ R}_{L} = 300 \Omega$	1.8				
		70000040		1.8 V $\leq$ V <sub>I</sub> $\leq$ 5.5 V, 0 mA $\leq$ I <sub>O</sub> $\leq$ 5 mA	0.0475				
		TPS60240		2.4 V $\leq$ V $_{I}$ $\leq$ 5.5 V, 0 mA $\leq$ I $_{O}$ $\leq$ 25 mA	3.2175	3.3	3.3825		
		TD000044		2.7 V $\leq$ V $_{I}$ $\leq$ 5.5 V, 0 mA $\leq$ I $_{O}$ $\leq$ 12 mA	4.075	-	5 405		
.,	<b>O</b> <i>i i i</i>	TPS60241		$3 \text{ V} \leq \text{V}_I \leq 5.5 \text{ V}, 0 \text{ mA} \leq \text{I}_O \leq 25 \text{ mA}$	4.875	5	5.125	.,	
VO	Output voltage	TD000040		1.8 V $\leq$ V <sub>I</sub> $\leq$ 5.5 V, 0 mA $\leq$ I <sub>O</sub> $\leq$ 12 mA	0.0005	0.7	0 7075	V	
l		TPS60242		$2.3 \text{ V} \leq \text{V}_I \leq 5.5 \text{ V}, 0 \text{ mA} \leq \text{I}_O \leq 25 \text{ mA}$	2.6325	2.7	2.7675		
		70000040		$1.8 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{O} \le 10 \text{ mA}$	0.005		0.075		
		TPS60243		$2.3 \text{ V} \leq \text{V}_I \leq 5.5 \text{ V}, 0 \text{ mA} \leq \text{I}_O \leq 25 \text{ mA}$	2.925	3	3.075		
		TD0000 40/0/0	Nominal	$2 V \leq V_I \leq 5.5 V$	12				
	<b>.</b>	TPS60240/2/3	Short circuit	V <sub>I</sub> = 2 V			80		
10	Output current	TPS60241	Nominal	$2.7 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$	12			mA	
			Short circuit	VI = 3.25 V			80	1	
fosc		Internal clock so	ource		100	160	220	kHz	
∨ <sub>n</sub>	Output noise	TPS60240/2/3		$V_I < 2.5$ V, $I_O = 5$ mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, $C_O = 4.7$ μF		170			
	voltage	TPS60241		V <sub>I</sub> = 2.7 V, I <sub>O</sub> = 5 mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, C <sub>O</sub> = 4.7 $\mu$ F		170		μV RMS	
V <sub>I(H)</sub>	EN	Logic high input	voltage VOH		1.3		5.5	V	
V <sub>I(L)</sub>	EN	Logic low input	voltage V <sub>OL</sub>		-0.2		0.4	V	
l <sub>l(H)</sub>	EN	Logic high input	current				100	nA	
II(L)	EN	Logic low input current					100	nA	
<sup>t</sup> (EN)	EN	Start-up time		$V_{O}$ > 90% of V(NOM) 0.1 mA $\leq$ I <sub>O</sub> $\leq$ 10 mA, C <sub>O</sub> = 1 $\mu$ F		0.5		ms	
		TPS60240		I <sub>O</sub> = 5 mA, V <sub>I</sub> = 1.8 V		89.6%			
	<b>-</b> <i>u</i> :	TPS60241		I <sub>O</sub> = 10 mA, V <sub>I</sub> = 2.7 V		90.8%			
η	Efficiency	TPS60242		I <sub>O</sub> = 10 mA, V <sub>I</sub> = 1.8 V		73%			
		TPS60243		I <sub>O</sub> = 10 mA, V <sub>I</sub> = 1.8 V		81%		1	



# electrical characteristics for TPS6024X at T<sub>A</sub> = 25°C, C<sub>I</sub> = C<sub>O</sub> =1 $\mu$ F, C<sub>1</sub> = C<sub>2</sub> = 1 $\mu$ F (unless otherwise noted), limits apply over the specified temperature range, –40°C to 85°C (continued)

PARAMETER		AMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Quiescent		$I_{O} = 0 \text{ mA}, V_{I} = 3 \text{ V}$		250	325	•
IQ current		In shutdown mode		0.1	1	μΑ	
	Thermal	Temperature activated			160		ŝ
	shutdown	Temperature deactivated			140		۰C

#### TYPICAL CHARACTERISTICS

#### **Table of Graphs**

			FIGURE
		vs Input voltage	1–4
	Efficiency	vs Output current	5–8
		vs Input voltage	9–12
Vo	Output voltage	vs Output current	13–16
•		vs Free-air temperature	17
		vs Input voltage	18
	Quiescent current	vs Free-air temperature	19
I <sub>L(sd)</sub>	Shutdown current	vs Free-air temperature	20
Vn	Output noise voltage	vs Output current	21
	Maximum output current	vs Input voltage	22–25
	Load transient response		26
	Start-up timing		27
	Line transient response		28
	Noise voltage spectrum		29
	Output voltage ripple	vs Time	30







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#### **TYPICAL CHARACTERISTICS**

NOTE: Scope triggered by voltage at flying capacitors, noise removed by averaging function and bandwidth limit 20 MHz.

V<sub>I</sub> = 3.3 V T<sub>A</sub> = 25°C

R2+

Figure 30

2.5 μs/div

 $C_I = C_O = 4.7 \ \mu F$ 





#### **APPLICATION INFORMATION**





Figure 32. 2-V to 3.3-V Low-Noise Converter

#### output voltage ripple

The output voltage ripple depends on the capacitors used. Table 1 illustrates the dependence between output voltage ripple and capacitor selection.

с <sub>і</sub>	с <sub>о</sub>	C <sub>1</sub>	C <sub>2</sub>	OUTPUT VOLTAGE RIPPLE [μVrms]
1 μF	1 μF	1 μF	1 μF	288
2.2 μF	2.2 μF	1 μF	1 μF	212
4.7 μF	4.7 μF	1 μF	1 μF	183
4.7 μF	1 μF	1 μF	1 μF	272
1 μF	4.7 μF	1 μF	1 μF	185

Table 1. Output Voltage Ripple and Capacitor Selection

NOTE: VI = 3.3 V, VO = 5 V, RL = 500  $\Omega$ , TA = 25°C



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#### **APPLICATION INFORMATION**

#### components

For the best output ripple performance, low-ESR ceramic capacitors are recommended (see Table 2).

PART	MANUFACTURER	PART NUMBER	VALUE	TOLERANCE	DIELECTRIC MATERIAL	PACKAGE	RATED VOLTAGE
<u>^</u>	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
CI	TDK	C2012X5R0J475K	4.7 μF	10%	X5R	0805	6.3
<u>_</u>	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
с <sub>О</sub>	TDK	C2012X5R0J475K	4.7 μF	10%	X5R	0805	6.3
C <sub>1</sub> , C <sub>2</sub>	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
CF	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10

#### **Table 2. Recommended Capacitors**

#### layout consideration

In order to get optimal noise behavior, keep the power lines to the capacitors and load as short as possible. Use of power planes is recommended.



Figure 33. Layout Diagram

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#### **APPLICATION INFORMATION**

Figure 34. Top Silkscreen



Figure 35. Top Layer

#### device family products

PART NUMBER	DESCRIPTION	
REG710	30-mA switched cap dc/dc converter	
REG711	50-mA switched cap dc/dc converter	
TPS60110	Regulated 5-V, 300-mA low-noise charge pump dc/dc converter	
TPS60111	Regulated 5-V, 150-mA low-noise charge pump dc/dc converter	



DGK (R-PDSO-G8)

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**MECHANICAL DATA** 

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187

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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TPS60240DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60240DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60242DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60243DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS



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#### compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1



# PACKAGE MATERIALS INFORMATION

9-Jan-2009



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60240DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60241DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60241DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60242DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60242DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60243DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60243DGKT	MSOP	DGK	8	250	190.5	212.7	31.8



10-Jun-2014

### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS60240DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60240DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60241DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60242DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60242DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYF	Samples
TPS60243DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60243DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



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#### **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

6-Jun-2013



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60240DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60241DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60241DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60242DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60243DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60243DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0

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